

High - Accuracy EPROM Programmable PLL Die for Crystal Oscillators

Features

- EPROM-programmable die for in-package programming of crystal oscillators
- High resolution PLL with 12-bit multiplier and 10-bit divider
- EPROM-programmable capacitor tuning array with Shadow register
- Twice programmable die (CY2037A, CY2037B^[1] and CY2037-2).
- Simple 4-wire programming interface
- On-chip oscillator runs from 10–30 MHz fundamental tuned crystal
- EPROM-selectable TTL or CMOS duty cycle levels
- Operating frequency
 - 1–133 MHz at 5V
 - 1–100 MHz at 3.3V
 - 1–66.6 MHz at 2.7V
- Sixteen selectable post-divide options, using either PLL or reference oscillator output
- Programmable power down (PD#) or OE pin (CY2037A, CY2037B, and CY2037-2)
- Frequency Select (CY2037-3)
- Programmable asynchronous or synchronous OE and power down (PD#) modes (CY2037A, CY2037B and CY2037-2)
- Low Jitter outputs typically
 - $< \pm 100$ ps (pk-pk) at 5V and $f > 33$ MHz
 - $< \pm 125$ ps (pk-pk) at 3.3V and $f > 33$ MHz
- 3.3V or 5V operation
- Small Die
- Controlled rise and fall times and output slew rate

Benefits

- Enables quick turnaround of custom oscillators
- Lowers inventory costs through stocking of blank parts
- Enables synthesis of highly accurate and stable output clock frequencies with zero or low PPM
- Enables fine-tuning of output clock frequency by adjusting C_{Load} of the crystal
- Enables reprogramming of programmed part, to correct errors, and control excess inventory
- Enables programming of output frequency after packaging
- Lowers cost of oscillator as PLL can be programmed to a high frequency using a low-frequency, low-cost crystal
- Duty cycle centered at 1.4V or $V_{DD}/2$
- Provides flexibility to service most TTL or CMOS applications
- Services most PC, networking, and consumer applications
- Provides flexibility in output configurations and testing
- Enables low-power operation or output enable function
- Enables two frequency options for meeting different industry standards, i.e., PAL/NTSC
- Provides flexibility for system applications, through selectable instantaneous or synchronous change in outputs
- Suitable for most PC, consumer, and networking applications
- Lowers inventory cost as same die services both applications
- Enables encapsulation in small-size, surface mount packages
- Has lower EMI than oscillators

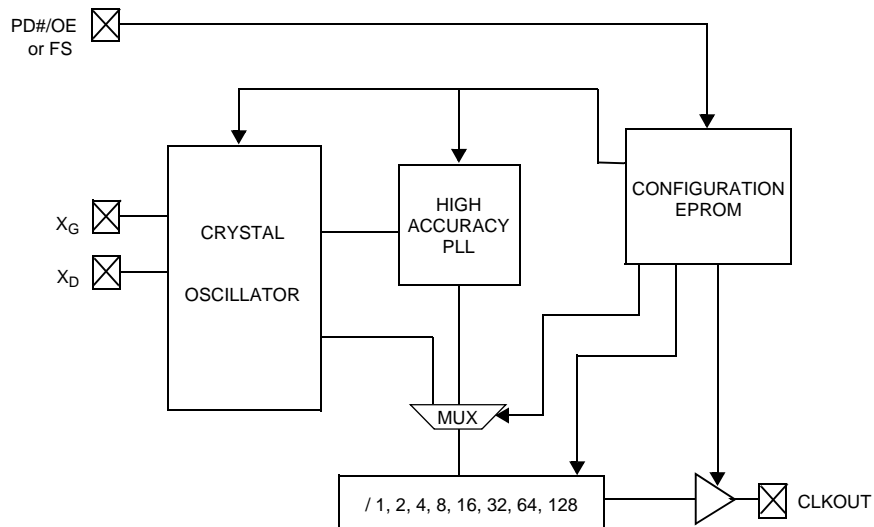
Table 1. Device Functionality: Output Frequencies

Parameter	Description	Condition	Min.	Max.	Unit
Fo	Output frequency	$V_{DD} = 4.5V-5.5V$	1	133	MHz
		$V_{DD} = 3.0V-3.6V$	1	100	MHz
		$V_{DD} = 2.7V-3.0V$	1	66	MHz

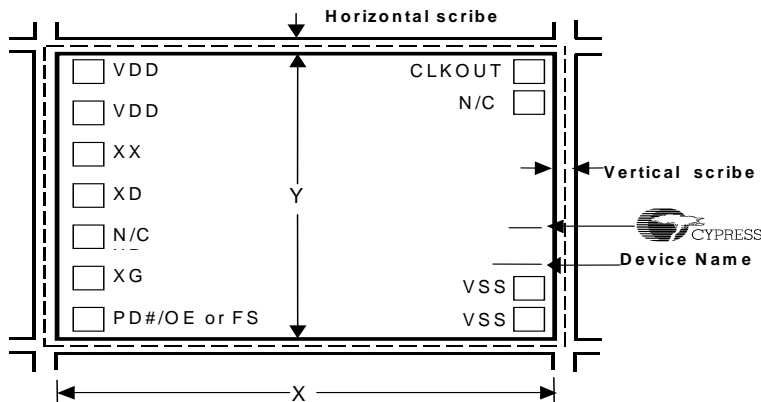
Note

1. The CY2037A and CY2037B are identical. However, the CY2037B is recommended for all new designs

Logic Block Diagram



Die Pad Description



Note:
 Active Die Size: X = 55.9 mils / 1420.1 μ m
 Scribe: X (horizontal)= 2.6 mils / 65.6 μ m
 Y (vertical)= 3.0 mils / 76.9 μ m
 Bond pad opening: 85 μ m x 85 μ m
 Pad pitch: 125 μ m x 125 μ m
 (Pad center to pad center)

Die Pad Summary

Name	Die Pad	Description	X Coordinate (μ m)	Y Coordinate (μ m)
V _{DD}	1,2	Voltage supply	124.7	855.6 , 731
V _{SS}	8,9	Ground	1291.35	99.6 , 225.2
X _D	4	Crystal connection.	124.7	481.8
X _X	3	No Connect ^[2]	124.7	606.4
X _G	6	Crystal connection.	124.7	232.6
PD#/OE or FS	7	CY2037A, CY2037B, and CY2037-2—EPROM programmable power down or output enable pad. CY2037-3—Frequency Select. Serves as V _{PP} in programming mode for all devices.	124.7	108
CLKOUT	11	Clock output. Also serves as three-state input during programming.	1282.45	901.8
N/C	5,10	No Connect. (Do not bond to these pads)	124.7,1282.45	357.2, 769.4

Note

2. For Customers not bonding the X_D or X_G pad to external pins, an alternative bonding option would be shorting the X_x pad to the X_D pad

Functional Description

The CY2037 is an EPROM programmable, high accuracy, PLL-based die designed for the crystal oscillator market. The die attaches directly to a low-cost 10–30 MHz crystal and can be packaged into 4-pin through-hole or surface mount packages. The oscillator devices can be stocked as blank parts and custom frequencies programmed in-package at the last stage before shipping. This enables fast-turn manufacture of custom and standard crystal oscillators without the need for dedicated, expensive crystals.

The CY2037 contains an on-chip oscillator and a unique oscillator tuning circuit for fine-tuning of the output frequency. The crystal C_{load} can be selectively adjusted by programming a set of seven EPROM bits. This feature can be used to compensate for crystal variations or to obtain a more accurate synthesized frequency.

The CY2037 uses EPROM programming with a simple 2-wire, 4-pin interface that includes V_{SS} and V_{DD} . Clock outputs can be generated up to 133 MHz at 5V or up to 100 MHz at 3.3V. The entire configuration can be reprogrammed one time, allowing programmed inventory to be altered or reused.

The CY2037 PLL die has been designed for very high resolution. It has a 12-bit feedback counter multiplier and a 10-bit reference counter divider. This enables the synthesis of highly accurate and stable output clock frequencies with zero or low PPM error. The clock can be further modified by eight output divider options of 1, 2, 4, 8, 16, 32, 64, and 128. The divider input can be selected as either the PLL or crystal oscillator output providing a total of sixteen separate output options. For further flexibility, the output is selectable between TTL and CMOS duty cycle levels.

The CY2037A, CY2037B and CY2037-2 also contain flexible power management controls. These parts include both power down (PD#) and OE features with integrated pull-up resistors. The PD# and OE modes have an additional setting to determine timing (asynchronous or synchronous) with respect to the output signal. When PD# or OE modes are enabled, CLKOUT is pulled low by a weak pull down. The weak pull down is easily overdriven by another active CLKOUTs for applications that require multiple CLKOUTs on a single signal path.

Controlled rise and fall times, unique output driver circuits, and innovative circuit layout techniques enable the CY2037 to have low jitter and accurate outputs, making it suitable for most PC, networking, and consumer applications.

On the other hand, the CY2037-3 contains a frequency select function in place of the power down and output enable modes. For example, consumer products often require frequency compatibility with different electrical standards around the world. With this frequency select feature, a product that incorporates the CY2037-3 could be compatible with both NTSC for North American and PAL for Europe simply by changing the FS line. The twice programmable feature is also absent in the

CY2037-3, because the second EPROM row is now being used for the alternate frequency.

EPROM Configuration Block

Table 2 summarizes the features that are configurable by EPROM. Please refer to the “7C8038x/7C8034X Programming Specification” for further details. The specification can be obtained from your Cypress factory representative.

Table 2. EPROM Adjustable Features

Adjust Frequency	Feedback counter value (P)
	Reference counter value (Q)
	Output divider selection
Oscillator Tuning (load capacitance values)	
Duty cycle levels (TTL or CMOS)	
Power management mode (OE or PD#)	
Power management timing (synchronous or asynchronous)	

PLL Output Frequency

The CY2037 contains a high-resolution PLL with 12-bit multiplier and 10-bit divider. The output frequency of the PLL is determined by the following formula:

$$F_{PLL} = \frac{2 \cdot (P + 5)}{(Q + 2)} \cdot F_{REF}$$

where P is the feedback counter value and Q is the reference counter value. P and Q are EPROM programmable values.

Power Management Features (except CY2037-3)

The CY2037 contains EPROM-programmable PD# and OE functions. If Powerdown is selected, all active circuitry on the chip is shut down when the control pin goes low. The oscillator and PLL circuits must re-lock when the part leaves Powerdown Mode. If Output Enable mode is selected, the output is tri-stated and weakly pulled low when the Control pin goes low. In this mode the oscillator and PLL circuits continue to operate, allowing a rapid return to normal operation when the Control input is deasserted.

In addition, the PD# and OE modes can be programmed to occur synchronously or asynchronously with respect to the output signal. When the asynchronous setting is used, the power down or output disable occurs immediately (allowing for logic delays) regardless of position in the clock cycle. However, when the synchronous setting is used, the part waits for a falling edge at the output before the power down or output enable signal is initiated, thus preventing output glitches. In either asynchronous or synchronous setting, the output is always enabled synchronously by waiting for the next falling edge of the output.

Crystal Oscillator Tuning Circuit

The CY2037 contains a unique tuning circuit to fine-tune the output frequency of the device. The tuning circuit consists of an array of eleven load capacitors on both sides of the oscillator drive inverter. The capacitor load values are EPROM programmable and can be increased in small increments. As

the capacitor load is increased the circuit is fine-tuned to a lower frequency. The capacitor load values vary from 0.17 pF to 8 pF for a 100:1 total control ratio. The tuning increments are shown in the table below. Please refer to the “7C8038x/7C8034x Programming Specification” for further details.

Figure 1. Crystal Oscillator Tuning Circuit

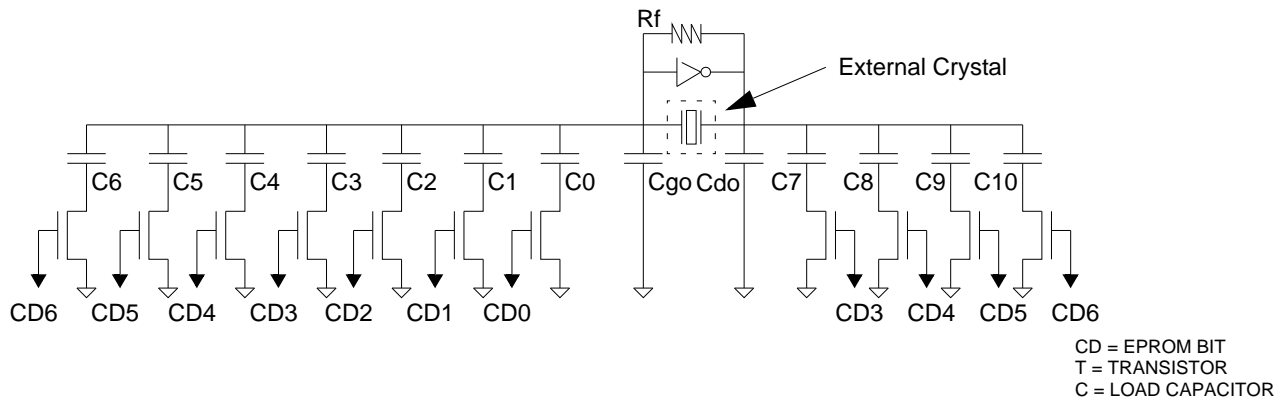


Table 3. Crystal Oscillator Parameter Table.

Parameter	Description	Min.	Typ.	Max.	Unit
R _f	Feedback resistor, V _{DD} = 4.5–5.5V	0.5	2	3.5	MΩ
	Feedback resistor, V _{DD} = 2.7–3.6V	1.0	4	9.0	MΩ
Capacitors have ± 20% Tolerance					
C _g	Gate capacitor		13		pF
C _d	Drain Capacitor		9		pF
C ₀	Series Cap		0.27		pF
C ₁	Series Cap		0.52		pF
C ₂	Series Cap		1.00		pF
C ₃	Series Cap		0.7		pF
C ₄	Series Cap		1.4		pF
C ₅	Series Cap		2.6		pF
C ₆	Series Cap		5.0		pF
C ₇	Series Cap		0.45		pF
C ₈	Series Cap		0.85		pF
C ₉	Series Cap		1.7		pF
C ₁₀	Series Cap		3.3		pF

Difference Between CY2037A/CY2037B and CY2037-2

The CY2037A/CY2037B contains a shadow register in addition to the EPROM register. The shadow register is an exact copy of the EPROM register and is the default register when the Valid bit is not set. It is useful when the prototype or production environment calls for measuring and adjusting the CLKOUT frequency numerous times. Multiple adjustments can be performed with the shadow register. Once the desired frequency is achieved the EPROM register is permanently programmed.

Some production flows do not require the use of the shadow register. If this is the case, then the CY2037-2 is the device of choice. The CY2037-2 has a disabled shadow register.

The CY2037-3 contains the shadow register.

Frequency Select Feature of CY2037-3

The CY2037-3 contains a frequency select function in place of the powerdown and the output enable functions. With the frequency select feature, customers can switch two different frequencies that are configured in the two EPROM rows. The definition of the Frequency Select pin (FS) is [Table 4](#).

Table 4. Frequency Select Pin Decoding for CY2037-3

FS Pin	Output Frequency
0	From EPROM Row 0 Configuration
1	From EPROM Row 1 Configuration

Absolute Maximum Ratings^[3]

Supply Voltage -0.5 to +7.0V
 Input Voltage -0.5V to $V_{DD}+0.5$

Storage Temperature (Non-Condensing).... 55°C to +150°C
 Junction Temperature -40°C to +100°C
 Static Discharge Voltage..... > 2000V
 (per MIL-STD-883, Method 3015)

Operating Conditions

Parameter	Description	Min.	Max.	Unit
V_{DD}	Supply Voltage (3.3V)	2.7	3.6	V
	Supply Voltage (5.0V)	4.5	5.5	V
T_{AJ} ^[4]	Operating Temperature, Junction	-10	+100	°C
C_{TTL}	Max. Capacitive Load on outputs for TTL levels $V_{DD} = 4.5-5.5V$, Output frequency = 1-40 MHz $V_{DD} = 4.5-5.5V$, Output frequency = 40-133 MHz		50	pF
			25	pF
C_{CMOS}	Max. Capacitive Load on outputs for CMOS levels $V_{DD} = 4.5-5.5V$, Output frequency = 1-66.6MHz $V_{DD} = 4.5-5.5V$, Output frequency = 66.6-133MHz $V_{DD} = 3.0-3.6V$, Output frequency = 1-40 MHz $V_{DD} = 3.0-3.6V$, Output frequency = 40-100 MHz $V_{DD} = 2.7-3.0V$, Output frequency = 1-66 MHz		50	pF
			25	pF
			30	pF
			15	pF
			15	pF
X_{REF}	Reference Frequency, input crystal. Fundamental tuned crystals only.	10	30	MHz
t_{PU}	Power-up time for all VDDs to reach minimum specified voltage (power ramps must be monotonic)	0.05	50	ms

Electrical Characteristics Over the Operating Range (Part was characterized in a 20-pin SOIC package with external crystal, Electrical Characteristics may change with other package types.)

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
V_{IL}	Low-level Input Voltage	$V_{DD} = 4.5V-5.5V$			0.8	V
		$V_{DD} = 2.7V-3.6V$			$0.2V_{DD}$	V
V_{IH}	High-level Input Voltage	$V_{DD} = 4.5V-5.5V$	2.0			V
		$V_{DD} = 2.7V-3.6V$	$0.7V_{DD}$			V
V_{OL}	Low-level Output Voltage	$V_{DD} = 4.5V-5.5V$, $I_{OL} = 16$ mA			0.4	V
		$V_{DD} = 2.7V-3.6V$, $I_{OL} = 8$ mA			0.4	V
V_{OHCMOS}	High-level Output Voltage, CMOS levels	$V_{DD} = 4.5V-5.5V$, $I_{OH} = -16$ mA	$V_{DD} - 0.4$			V
		$V_{DD} = 2.7V-3.6V$, $I_{OH} = -8$ mA	$V_{DD} - 0.4$			V
V_{OHTTL}	High-level Output Voltage, TTL levels	$V_{DD} = 4.5V-5.5V$, $I_{OH} = -8$ mA	2.4			V
I_{IL}	Input Low Current	$V_{IN} = 0V$			10	μA
I_{IH}	Input High Current	$V_{IN} = V_{DD}$			5	μA
I_{DD}	Power Supply Current, Unloaded	$V_{DD} = 4.5V-5.5V$, Output frequency ≤ 133 MHz			45	mA
		$V_{DD} = 2.7V-3.6V$, Output frequency ≤ 100 MHz			25	mA
I_{DDS} ^[5]	Stand-by current	$V_{DD} = 2.7V-3.6V$		10	50	μA
R_{UP}	Input Pull-up Resistor	$V_{DD} = 4.5V-5.5V$, $V_{IN} = 0V$	1.1	3.0	8.0	MΩ
		$V_{DD} = 4.5V-5.5V$, $V_{IN} = 0.7V_{DD}$	50	100	200	kΩ
I_{OE_CLKOUT}	CLKOUT Pull-down current	$V_{DD} = 5.0$		20		μA

Notes

3. Stresses greater than listed may impair the life of the device.
4. This product is sold in die form so operating conditions are specified for the die, or junction temperature
5. If external reference is used, it is required to stop the reference (set reference to LOW) during power down

Output Clock Switching Characteristics Over the Operating Range^[6]

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
t _{1w}	Output Duty Cycle at 1.4V, V _{DD} = 4.5–5.5V t _{1w} = t _{1A} ÷ t _{1B}	1–40 MHz, C _L ≤ 50 pF	45		55	%
		40–66 MHz, C _L ≤ 15 pF	45		55	%
		66–125 MHz, C _L ≤ 25 pF	40		60	%
		125–133 MHz, C _L ≤ 15 pF	40		60	%
t _{1x}	Output Duty Cycle at V _{DD} /2, V _{DD} = 4.5–5.5V t _{1x} = t _{1A} ÷ t _{1B}	1–66.6 MHz, C _L ≤ 25 pF	45		55	%
		66.6–125 MHz, C _L ≤ 25 pF	40		60	%
		125–133 MHz, C _L ≤ 15 pF	40		60	%
t _{1y}	Output Duty Cycle at V _{DD} /2, V _{DD} = 3.0–3.6V t _{1y} = t _{1A} ÷ t _{1B}	1–40 MHz, C _L ≤ 30 pF	45		55	%
		40–100 MHz, C _L ≤ 15 pF	40		60	%
t _{1z}	Output Duty Cycle at V _{DD} /2, V _{DD} = 2.7–3.0V t _{1y} = t _{1A} ÷ t _{1B}	1–40 MHz, C _L ≤ 15 pF 40–66.6 MHz, C _L ≤ 10 pF	40 40		60 60	% %
t ₂	Output Clock Rise Time	Between 0.8V–2.0V, V _{DD} = 4.5V–5.5V, C _L = 50 pF			1.8	ns
		Between 0.8V–2.0V, V _{DD} = 4.5V–5.5V, C _L = 25 pF			1.2	ns
		Between 0.8V–2.0V, V _{DD} = 4.5V–5.5V, C _L = 15 pF			0.9	ns
		Between 0.2V _{DD} –0.8V _{DD} , V _{DD} = 4.5V–5.5V, C _L = 50 pF			3.4	ns
		Between 0.2V _{DD} –0.8V _{DD} , V _{DD} = 3.0V–3.6V, C _L = 30 pF			4.0	ns
		Between 0.2V _{DD} –0.8V _{DD} , V _{DD} = 2.7V–3.6V, C _L = 15 pF			2.4	ns
t ₃	Output Clock Fall Time	Between 0.8V–2.0V, V _{DD} = 4.5V–5.5V, C _L = 50 pF			1.8	ns
		Between 0.8V–2.0V, V _{DD} = 4.5V–5.5V, C _L = 25 pF			1.2	ns
		Between 0.8V–2.0V, V _{DD} = 4.5V–5.5V, C _L = 15 pF			0.9	ns
		Between 0.2V _{DD} –0.8V _{DD} , V _{DD} = 4.5V–5.5V, C _L = 50 pF			3.4	ns
		Between 0.2V _{DD} –0.8V _{DD} , V _{DD} = 3.0V–3.6V, C _L = 30 pF			4.0	ns
		Between 0.2V _{DD} –0.8V _{DD} , V _{DD} = 2.7V–3.6V, C _L = 15 pF			2.4	ns
t ₄	Start-up Time Out of Power Down	PD# pin LOW to HIGH ^[7]		1	2	ms
t _{5a}	Power Down Delay Time (synchronous setting)	PD# pin LOW to output LOW (T = period of Output clk)		T/2	T+10	ns
t _{5b}	Power Down Delay Time (asynchronous setting)	PD# pin LOW to output LOW		10	15	ns
t ₆	Power Up Time	From power on ^[7]		1	2	ms
t _{7a}	Output Disable Time (synchronous setting)	OE pin LOW to output Hi-Z (T = period of output clk)		T/2	T+10	ns
t _{7b}	Output Disable Time (asynchronous setting)	OE pin LOW to output Hi-Z		10	15	ns
t ₈	Output Enable Time (always synchronous enable)	OE pin LOW to HIGH (T = period of output clk)		T	1.5T+25	ns
t ₉	Peak-to-Peak Period Jitter	V _{DD} = 4.5V–5.5V, F _o > 33 MHz, VCO > 100 MHz		±100	±125	ps
		V _{DD} = 2.7V–3.6V, F _o > 33 MHz, VCO > 100 MHz		±125	±200	ps
		V _{DD} = 2.7V–5.5V, F _o < 33 MHz		±250	1% of F _O	ps

Notes

6. Not all parameters measured in production testing.

7. Oscillator start time cannot be guaranteed for all crystal types. This specification is for operation with AT cut crystals with ESR < 70 ohms.

Switching Waveforms

Figure 2. Duty Cycle Timing (t_{1w} , t_{1x} , t_{1y} , t_{1z})

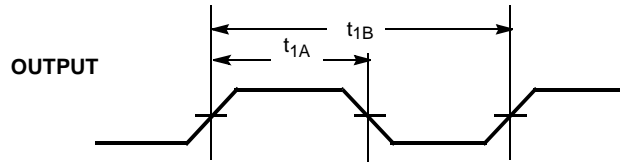


Figure 3. Output Rise/Fall Time

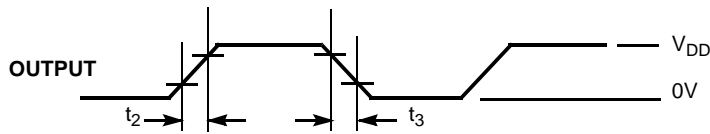


Figure 4. Power Down Timing (synchronous and asynchronous modes)

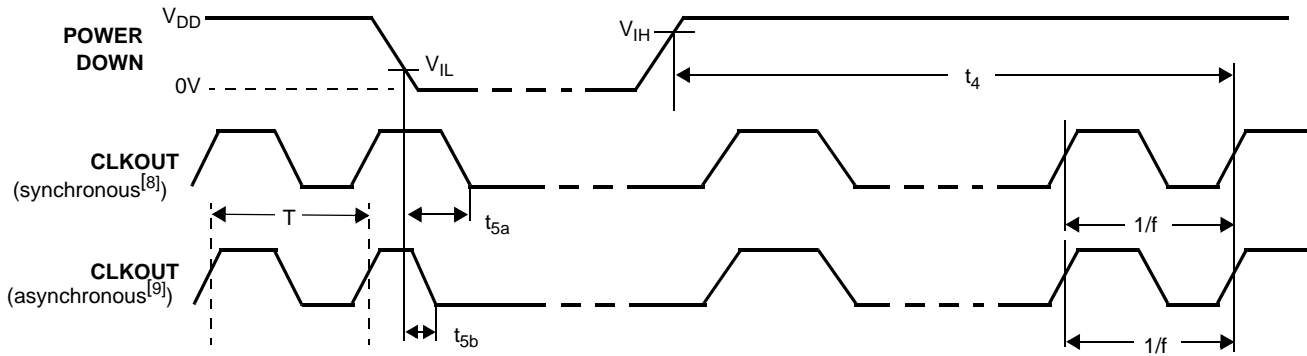
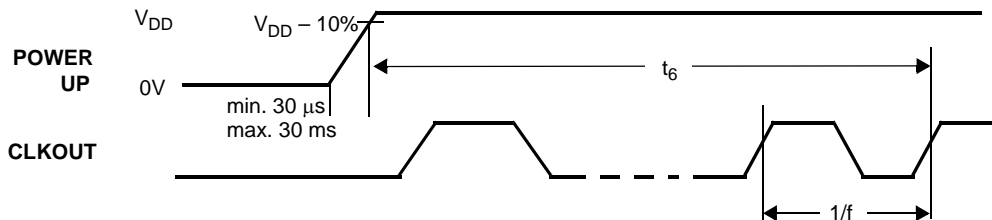


Figure 5. Power-up Timing



Notes

8. In synchronous mode the power down or output tri-state is not initiated until the next falling edge of the output clock.
9. In asynchronous mode the power down or output tri-state occurs within 25 ns regardless of position in the output clock cycle.

Ordering Information^[10]

Ordering Code	Type	Wafer Thickness	Operating Range
CY2037AWAF ^[11]	Wafer	14 ± 0.5 mils	-10°C to +100°C
CY2037-2WAF ^[11]	Wafer	14 ± 0.5 mils	-10°C to +100°C
CY2037-3WAF ^[11]	Wafer	14 ± 0.5 mils	-10°C to +100°C
CY2037BWAF	Wafer	14 ± 0.5 mils	-10°C to +100°C
CY2037B-11WAF	Wafer	11 ± 0.5 mils	-10°C to +100°C

Note

10. The only difference between the CY2037A/CY2037B and the CY2037-2 is that the CY2037-2 has the shadow register disabled. The CY2037-3 replaces the power-down options with a Frequency Select, and contains the shadow register.

11. The CY2037B is recommended for all new designs

Document History Page

Document Title: CY2037 High-Accuracy EPROM Programmable PLL Die for Crystal Oscillators				
Document Number: 38-07354				
REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	112248	03/01/02	DSG	Change from Spec number: 38-00679 to 38-07354
*A	121857	12/14/02	RBI	Power-up requirements added to Operating Conditions Information
*B	291092	See ECN	RGL	Updated Min. Operating Temperature, Junction
*C	522769	See ECN	RGL	Added CY2037B information. Updated absolute maximum Junction temperature specification. Updated Ordering information table. Added Die Pad description and coordinates
*D	804376	See ECN	RGL	Minor Change: To post on web